

Testing of ASIC replacement on the Barrel Kapton hybrid

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- **Jig:**

- 8 mm x 8 mm x 12 mm Cu block
- Trench of 6.5 mm width and 0.3 mm depth
- Cu block attached to the soldering tip

- **Sample:**

- K1 hybrid with Carbon/carbon bridge
- 5 Dummy IC's (silicon) glued (with conducting epoxy) on the hybrid
- PT100 glued on the backside of the bridge
- Hybrid attached to a fixture with a 1 mm silicon rubber sheet

- **Process:**

- Temperature of the Cu block = 250 °C
- Touch the ASIC and gently apply “twist”, until the chip moves
- Time required and temp. of the backside of the bridge
(7 s, 62 °C), (5 s, 52°C), (4 s, 48°C), (4 s, 50°C), (7 s, 61°C)

- **Conclusion:**

- Could remove the IC, easier when the chip was heated faster
- “Twist” is important
- Future plan: make a vacuum chuck to take the chip off

